



Material Content Data Sheet



Sales Product Name		IPG20N06S4L-14A		Issued		29. August 2013			
MA#		MA001096388							
Package		PG-TDSON-8-10		Weight*		99.49 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	2.690	2.70	2.70	27039	27039	
leadframe	non noble metal	iron	7439-89-6	0.046	0.05		467		
	inorganic material	phosphorus	7723-14-0	0.014	0.01		140		
	non noble metal	copper	7440-50-8	46.380	46.61	46.67	466176	466783	
wire	non noble metal	aluminium	7429-90-5	0.723	0.73	0.73	7267	7267	
encapsulation	organic material	carbon black	1333-86-4	0.089	0.09		891		
	plastics	epoxy resin	-	6.293	6.33		63251		
	inorganic material	silicondioxide	60676-86-0	37.935	38.13	44.55	381290	445432	
leadfinish	non noble metal	tin	7440-31-5	1.396	1.40	1.40	14036	14036	
plating	inorganic material	phosphorus	7723-14-0	0.001	0.00		14		
	non noble metal	nickel	7440-02-0	0.603	0.61	0.61	6062	6076	
solder	non noble metal	tin	7440-31-5	0.066	0.07		667		
	noble metal	silver	7440-22-4	0.083	0.08		834		
	non noble metal	lead	7439-92-1	3.170	3.19	3.34	31866	33367	
*deviation	< 10%					Sum in total:	100,00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com